

Megaposit SPR 220-7.0 – run sheet

Rohm and Haas Electronic Materials

nanyte.com/photoresists/spr220-7 · last updated 2026-07-26

Thickness: 5.5–52 μm

Softbake: 115 °C · 1.5 min · hotplate

Exposure dose – dose by film thickness · at 436 nm

Film thickness	Dose
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7 μm	470 mJ/cm ²
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Post-exposure bake: 115 °C · 1.5 min

Develop: Developer MF-24A (0.24N MIF – metal-ion-free TMAH developer) · Dilution 0.24N (MF-24A is the 0.24N-normality developer in Rohm and Haas's MF line; SPR220 is "optimized for 0.24N developers", with 0.26N (MF-26A) offered as an alternative for thicker films or high-throughput processes) · Time 2 min · Method puddle